Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	6 X 6 X 0.75 (3.9 EP)
Lead Count	40
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.12E-02	86.2	862000	48.03	480262
Thermosets	Epoxy resin	Proprietary	3.56E-03	6.0	60000	3.34	33429
Thermosets	Phenol resin	Proprietary	3.56E-03	6.0	60000	3.34	33429
Other inorganic materials	Metal Hydroxide	Proprietary	8.90E-04	1.5	15000	0.84	8357
Other inorganic materials	Carbon black	1333-86-4	1.78E-04	0.3	3000	0.17	1671
Subtotal			5.94 E-02	100.00	1000000	55.71	557148

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.85 E-02	97.50	975000	36.13	361251
Copper & its alloys	Iron	7439-89-6	9.28 E-04	2.35	23500	0.87	8707
Copper & its alloys	Zinc	7440-66-6	4.74 E-05	0.12	1200	0.04	445
Copper & its alloys	Phosphorus	7723-14-0	1.18 E-05	0.03	300	0.01	111
Subtotal			3.95 E-02	100.00	1000000	37.05	370514

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.95 E-05	100.0	1000000	0.04	371

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.52 E-03	100.0	1000000	2.37	23653

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.24 E-03	100.0	1000000	1.16	11636

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.36 E-03	100.0	1000000	3.15	31491

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.67 E-04	66.34	663400	0.34	3441
Thermoset	Epoxy resin	Proprietary	3.10 E-05	5.61	56100	0.03	291
Other organic materials	Aliphatic acid anhydride	Proprietary	3.10 E-05	5.61	56100	0.03	291
Other organic materials	2,6 diglycidyl phenyl allyl ether oligomer	Proprietary	3.10 E-05	5.61	56100	0.03	291
Other organic materials	Epoxy derivative	Proprietary	3.10 E-05	5.61	56100	0.03	291
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	3.10 E-05	5.61	56100	0.03	291
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	3.10 E-05	5.61	56100	0.03	291
Subtotal			5.53 E-04	100.0	1000000	0.52	5187

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.07 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES